Stock Code: **7828**

INNOS
創新服務股份有限公司

Innostar Service Inc.

Q2 2026 Operations Overview & Outlook

2026 September

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1.Company Overview & Philosophy

INNOS empowers your manufacturing process and product innovation with expert, end-to-end solutions

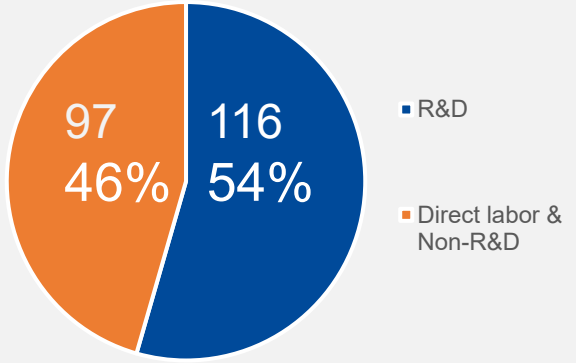
Company Overview

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INNOS® 創新服務股份有限公司
InnoStar Service, Inc.

- **Established: 2004**
- **Paid-in Capital:** NTD 405 million
- **Employees:** 213
- (as of September 2026)
- **Locations**
  - Hsinchu Plant
  - Taichung Headquarters(Xing-an Plant, Zhong-shan Plant)
  - Kaohsiung Office
- **Core Businesses**
  - Development, manufacturing, and sales of semiconductor automation equipment
  - Advanced packaging solutions
  - Development, manufacturing, and sales of advanced packaging components
  - Probe card repair services and sales of related materials

R&D talent accounts for **54%** of total headcount.





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Key Milestones

2004

- Company established
- Launched first-gen automatic plastic lens-cutting machine
- **Pioneered automation revolution for optical industry**

2014

- **Expanded into advanced semiconductor testing, developed MEMS Probe Card Assembly Equipment for wafer testing**
- **Pioneered automation revolution for probe card industry**

2016

OEM service of MEMS probe assembly for leading foundries, having processed more than 300 million units

2022

Auto Probe Assembly Machine adopted by leading probe card makers

2024

High-density Cu Pillar applied to WIFI modules with substantial sample shipments

Probe Assembly Machine adopted at scale by probe card makers



2025

High-density Cu Pillar applied to power modules, TGV, and PLP modules

- **Technoprobe became strategic investor**
- **Launched comprehensive MEMS probe card automation solutions**



2026

To verify and mass-produce High-density Cu Pillar modules

- **To expand the MEMS probe card equipment lineup**
- **To establish and realize probe card repair capacity**

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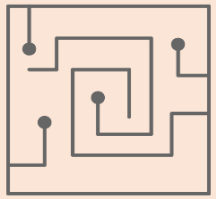
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2. Industry & Operations Overview

Industry Overview

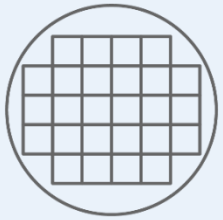
Upstream



IC Design

Foundry

Midstream

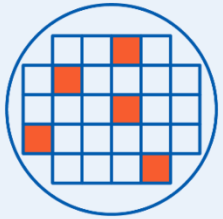


IC/Wafer Manufacturing

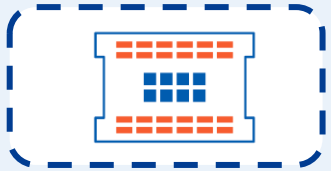
Process & Testing Equipment

Photomask

Chemical



IC Testing (Chip Probing)



Probe Cards for Wafer Testing



Probe Assembly and Related Automation Equipment Material Kits & Contract Service

Downstream



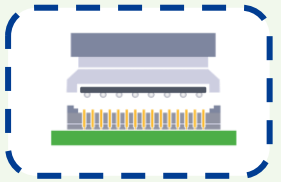
IC Packaging

IC Testing

Process & Testing Equipment

Substrate

Lead Frame

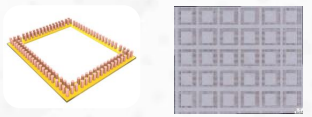


Final Test

IC Distribution



CoWoS Substrate Component Repair Equipment



High-density Cu Pillar Modules



Pogo Pin Assembly & Related Automation Equipment

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Product Portfolio

Probe Card Full-Line Equipment Automation Solutions

- Laser Drilling Machine
- Guide Plate Inspection and Lamination Machine
- Dual-arm Needle Assembly Machine
- Probe Card Inspection Machine
- Laser Reshaping Machine, Laser Cleaning Machine
- Auto Probe Change Machine
- Probe Binning and Aligning Machine
- CoWoS FT Auto Probe Assembly (90um) and Inspection Machine



MEMS Probe Card Repair Lineup

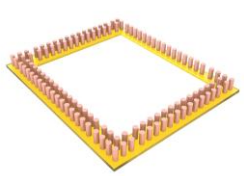
Semiconductor High-Precision Processing

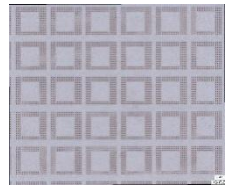
- High-Precision Laser Cutting Machine
- Mini LED Laser Repair Equipment
- Laser De-coating Machinery
- MEMS Mirrors Precision Assembly Machine
- CoWoS Substrate Component Repair Equipment
- High-Precision Spot Welding Machine

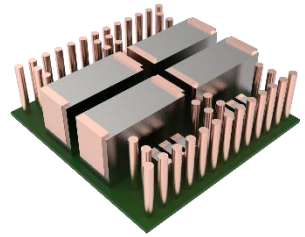


Advanced Packaging

- High-Density Cu Pillar Module for WiFi modules
- High-Density Cu Pillar Module for power modules
- Interposer (10:1) Cu Pillar TGV







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End-to-End Automation Solutions for MEMS Probe Cards

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INNOS End-to-End Probe Card Manufacturing and Repair Equipment

Laser Drilling Machine (LS-11)	Guide Plate Inspection and Lamination Machine (PHIA-02)	Dual-arm Needle Assembly Machine (AT-105/AT106)	Probe Card Inspection Machine (PCR-02)	Laser Reshaping Machine (PHR02) & Laser Cleaning Machine (PHC-02)	Auto Probe Change Machine (PIR-02)	Probe Binning and Aligning Machine (PSA-01)
Development completed	Completion expected 1Q26	Development completed	Development completed	Development completed	Development completed	Development completed



Conventional Probe Card Manufacturing Processes

Laser drilling machine	Manual & semi-auto lamination	Manual needle assembly	Manual microscopic inspection	Semi-auto laser cleaning	Manual probe replacement & measurement	Manual binning

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Three-Pillar Product Lines

#	INNOS'MEMS Probe Card Solutions	Customers	2026 Q1	Q2	Q3	Q4
Automated Probe Card Equipment	1. Dual-arm Probe Assembly machine	Probe card maker	→	→	→	→
	2. Probe Card Repair Lineups: Probe replacement, probe reshaping, probe card inspection, laser cleaning, and sorting & alignment machines.	Probe card maker		→	→	→
	3. Probe Card Automation Processing Equipment: Laser drilling, automated alignment & lamination, reshaping, electrical testing, and pin adjustment machines.	Probe card maker			→	→
Material Kits & Contract Service	1 Probe Card Contract Service: pin insertion/reshaping/repair	Probe card maker	→	→	→	→
	2. Probe Card Material Kits	Probe card maker		→	→	→
Cu Pillar Products	1. Cu Pillar Modules: AiP, power modules	OSATs Antenna module vendors Power supply IC vendors			→	→
	2. TVG-ICP (Cu pillar inserted) core layer substrates	AI networking chip vendors	→	→	NTI →	→

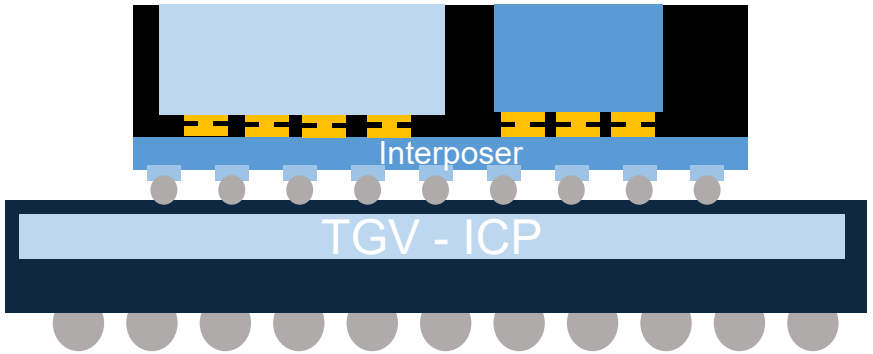
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INNOS

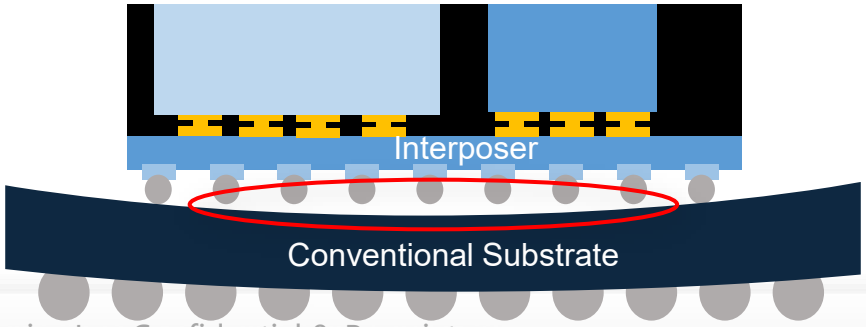
TGV-ICP (Through Glass Via with Inserted Cu Pillar)

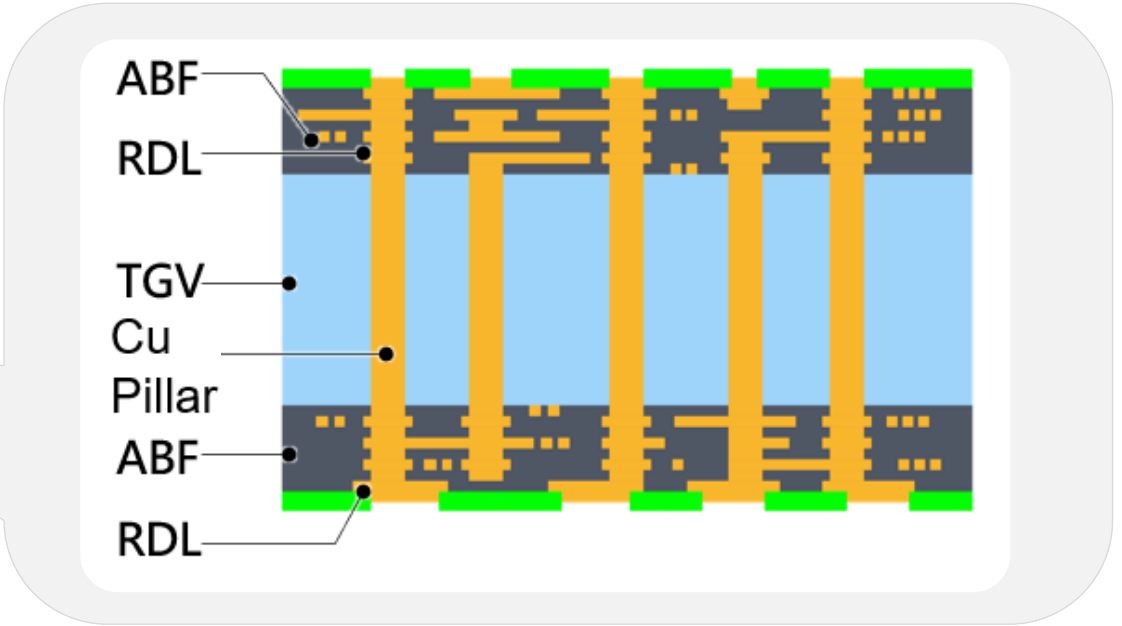
TGV – ICP for substrates addresses critical large-form-factor demands across CoWoS (-S/R/L), CoPoS, and other advanced packaging processes.

Glass-substrate TGV-ICP delivers high rigidity and zero warpage.



Conventional fiberglass substrates: Low rigidity and high warpage risk, leading to interposer bonding failure

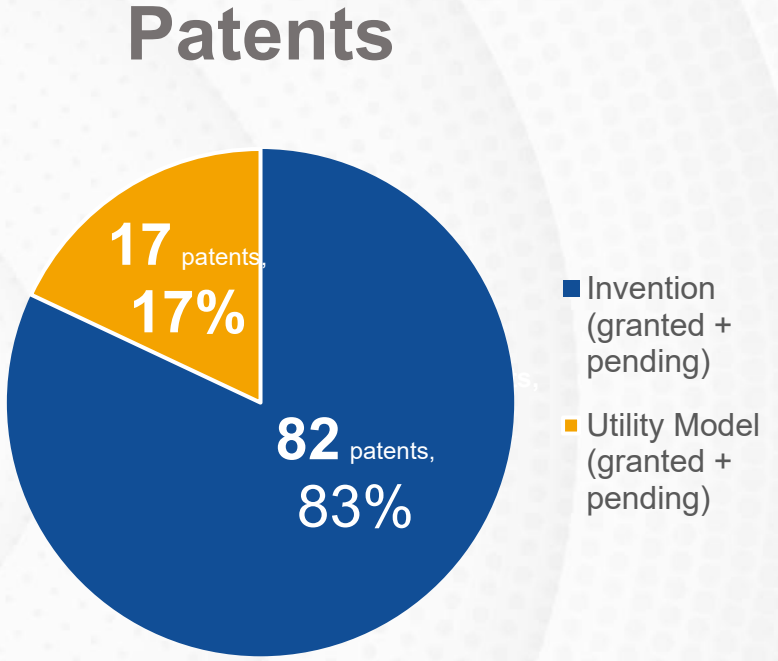




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Patents

Patent Category	Granted		Pending	
	Invention	Utility Model	Invention	Utility Model
Semiconductor advanced process equipment	15	1	5	1
Advanced packaging equipment and related products	14	7	23	0
Others	14	8	11	0
Subtotal	43	16	39	1



As of now, INNOS holds 59 patents (43 inventions and 16 utility model patents), with 40 additional applications pending (39 inventions and 1 utility model patents).

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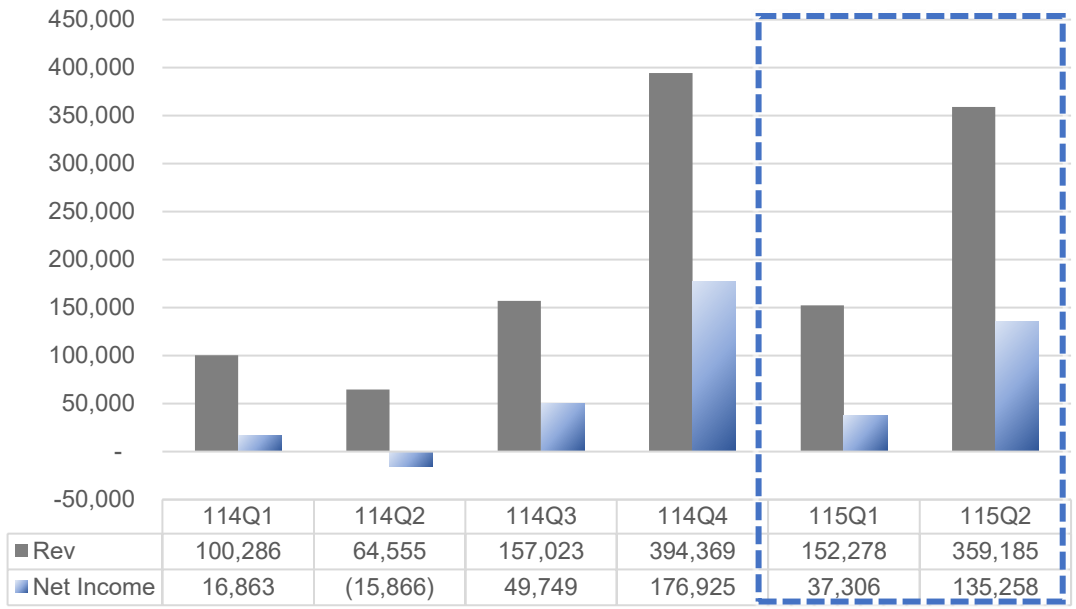
3. 2Q26 Performance & Outlook

Operating Performance

Unit: NTD thousands; NTD

	2025H1	2026H1	YOY
Revenue	164,841	511,463	Growth 210.28%
Gross margin	65.80%	79.44%	Increased by 13.64%
Operating margin	13.60%	39.39%	Increased by 25.79%
EPS	0.03	4.52	Increased by NT$4.49
EBITDA margin	9.32%	45.73%	Increased by 36.41%

Unit: NTD thousands



	114Q1	114Q2	114Q3	114Q4	115Q1	115Q2
Rev	100,286	64,555	157,023	394,369	152,278	359,185
Net Income	16,863	(15,866)	49,749	176,925	37,306	135,258

- Revenue for 2026H1 increased by 210.28% YoY, primarily driven by advances in semiconductor process technologies and strong end-customer demand fueled by AI applications. INNOS successfully developed Dual-arm Needle Assembly Machine for MEMS probe cards and integrated automation solutions for complete production lines, supporting steady shipments of MEMS probe card-related equipment. As a result, the Company maintained a high gross margin and continued its upward revenue growth trend.
- Operating expenses for 2026H1 were higher than the same period last year, mainly due to continued increases in R&D investment, workforce expansion, and higher employee compensation/bonuses and directors' remuneration accrued in line with revenue and profit growth.

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Outlook
Three Core Pillars for Operational Growth

Semiconductor Equipment

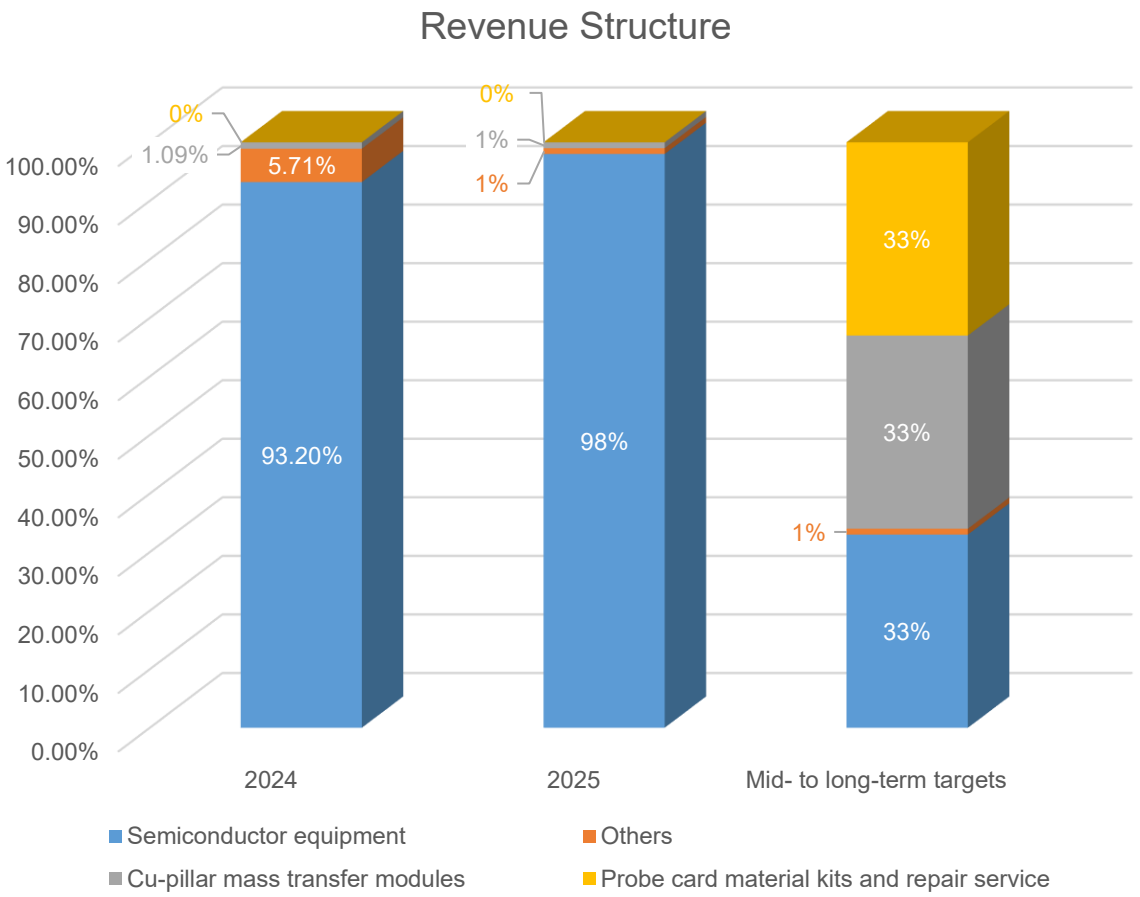
- Dual-arm Needle Assembly Machine are benefiting from stronger growth momentum among end customers, with shipments expected to increase significantly going forward.
- Probe card repair automation equipment is progressively completing customer validation and moving into shipment, which is expected to provide a new growth driver in 2H 2026.
- A new generation of advanced probe card-related equipment is currently under development, with customer validation scheduled to begin progressively in 2H 2026. These new products are expected to contribute to revenue growth in 2027.

Probe Card Material Kits and Repair Service

- Transitioning into a probe card material kit supplier
- Probe repair services, reducing turnaround time on conventional repair
- Increasing recurring revenue from PC material kit supply and repair services.

Cu Pillar Mass Transfer Modules

- Focusing on power module and TGV CoWoS packaging market
- Mass adoption in 2026 across RF/network communication and high-speed TGV transmission modules.
- Mass adoption in 2027 for AI power modules.



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